Data Sheet

V 1.0 / Oct. 2019

MSM42A3722H9KR

Analog output MEMS microphone

苏州敏芯微电子技术股份有限公司 MEMSensing Microsystems (Suzhou, China) Co., Ltd.



GENERAL DESCRIPTION

MSM42A3722H9KR is an omnidirectional, Top-ported, analog output MEMS microphone. It has high performance and reliability.

MSM42A3722H9KR is available in a thin 3.76 mm × 2.24 mm × 1.1 mm metal can LGA package. It is SMT compatible with no sensitivity degradation.

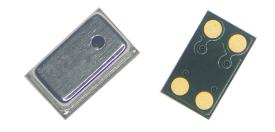
APPLICATIONS

- ♦ Mobile Phone
- ♦ Laptop
- ♦ Tablet computer
- ♦ Bluetooth headset
- ♦ Earphone
- ♦ Wearable intelligent equipment

FEATURES

- ♦ Low Noise
- ♦ Omnidirectional
- ♦ Standard SMD Reflow
- Compatible with Sn/Pb and Pb-free solder processes
- ♦ RoHS/Halogen free compliant

PRODUCT VIEW



ABSOLUTE MAXIMUM RATINGS

| Parameter | Maximum value | Unit |
|----------------------|---------------|--------|
| Supply Voltage | -0.3 to 4.0 | V |
| Sound Pressure Level | 140 | dB SPL |
| Storage temperature | -40 to 100 | °C |

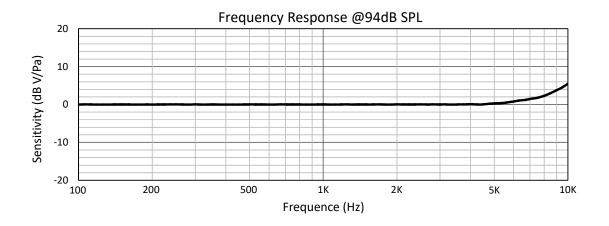
Stresses exceeding these "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation at these or any other conditions beyond those indicated under "Acoustic & Electrical Specifications" is not implied. Exposure beyond those indicated under "Acoustic & Electrical Specifications" for extended periods may affect device reliability.

ACOUSTIC & ELECTRICAL SPECIFICATIONS

| All data tak | en at 25°C, Re | elative Humidit | y 45±5% unles | s otherwis | e specified | |
|---|---------------------------|-----------------------|------------------------------|------------|--|--|
| | Limits | | | unit | condition | |
| | Min. | Nom. | Max. | | | |
| Directivity | (| Omni direction | al | | | |
| Sensitivity | -45 | -42 | -39 | dB | @1kHz ref 1V/Pa | |
| Operation voltage | 1.5 | - | 3.6 | V | | |
| Freq. range | Refer to | the frequency graphic | response | Hz | Ref to sensitivity@1kHz | |
| Sensitivity loss across supply voltage | No change | e across the vo | ltage range | dB | | |
| Signal to noise ratio | - | 58 | - | dB | 20 kHz bandwidth, A-weighted | |
| THD | - | 0.1 | - | % | 94dB SPL @1kHz S =Nom, Rload > 2 k | |
| AOP | - | 130 | - | dB SPL | 10% THD @1kHz S =Nom, Rload > 2 k | |
| Polarity | Increasing output voltage | | Increasing sound pressure | | | |
| Out impedance | - | 200 | - | Ω | @1kHz | |
| DC Output | | 0.7 | | V | | |
| PSRR | - | 70 | - | dB | 200mVpp sine wave @ 1 kHz, VDD = 1.8V | |
| PSR | - | -100 | - | dBV(A) | 100 mVpp square wave@ 217 Hz, VDD = 1.8V, A-weighted | |
| Current consumption | - | 150 | 170 | μΑ | | |

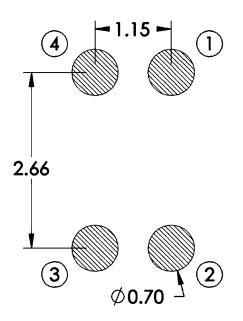


TYPICAL FREQUENCY RESPONSE

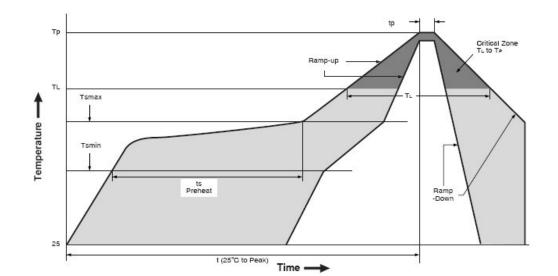


SMT Parameters:

1. Recommend PCB land pattern layout: (unit: mm)







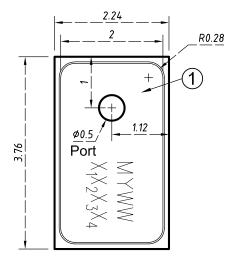
| Description | Parameter | Pb-free |
|---|-------------------------------------|-------------------|
| Average ramp-up rate | T _{smax} to T _P | 3°C/sec max |
| Preheat | | |
| Minimum temperature | T _{SMIN} | 150 °C |
| Maximum temperature | T _{SMAX} | 200 °C |
| Time(T _{SMIN} to T _{SMAX}) | ts | 60 sec to 180 sec |
| Ramp-up rate | T_{SMAX} to T_L | 1.5~2 °C/sec |
| Time maintained above liquidus temperature | tL | 60 sec to 150 sec |
| Liquidus temperature | ΤL | 217 °C |
| Peak temperature | T _P | 260 °C |
| Time within 5°C of actual peak temperature | tP | 20 sec to 40 sec |
| Ramp-down rate | T _P to T _{smax} | 6 °C/sec max |
| Time 25 °C (t25 °C) to peak temperature | t | 8 minutes max |

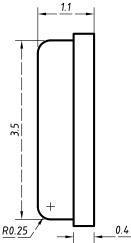
NOTE: When MEMS MIC is soldered on PCB, the reflow profile is set according to solder paste and the thickness of PCB etc.

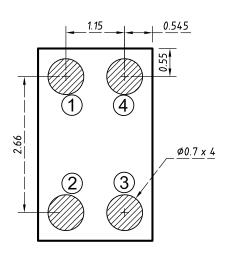


OUTLINE DIMENSIONS AND PIN DEFINITION:









TOP VIEW

SIDE VIEW

BOTTOM VIEW

| PIN function description | | |
|--------------------------|----------|--|
| PIN# | Function | |
| 1 | VDD | |
| 2 | GND | |
| 3 | GND | |
| 4 | OUT | |

| ltem | Dimension | Tolerance |
|--------------------|-----------|------------|
| Length (L) | 3.76 | ±0.10 |
| Width (W) | 2.24 | \pm 0.10 |
| Height (H) | 1.10 | ±0.10 |
| Acoustic Port (AP) | Ø0.5 | \pm 0.05 |

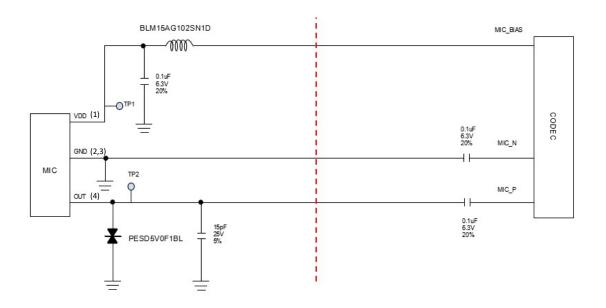
Dimensions are in millimeters, tolerance is ±0.15mm unless otherwise specified.

| | м | Memsensing |
|----------------|----------------|---------------|
| MYWW | Y | Year(A~Z) |
| $X_1X_2X_3X_4$ | ww | Week |
| · | $X_1X_2X_3X_4$ | Serial Number |



RECOMMENDED INTERFACE CIRCUIT:

Recommended Application Example (differential amplification circuit)



NOTE: It is recommended that the components on the left side of red line be placed close to MIC, and components on the right side of red line be placed close to codec.



- (A) MSL (moisture sensitivity level) Class 1.
- (B) Maximum of 3 reflow cycles is recommended.
- (C) In order to minimize device damage:

Do not board wash or clean after the reflow process.

Do not brush board with or without solvents after the reflow process.

Do not directly expose to ultrasonic processing, welding, or cleaning.

Do not insert any object in port hole of device at any time.

Do not apply air pressure into the port hole.

Do not pull a vacuum over port hole of the microphone.

Do not apply a vacuum when repacking into sealed bags at a rate faster than 0.5 atm/sec.

STORAGE AND TRANSPORTATION

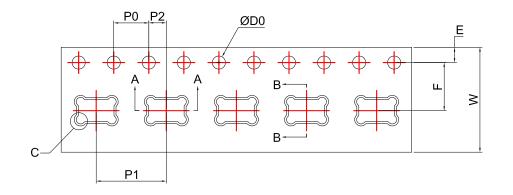
- (A) Keep MEMS MIC in warehouse with less than 75% humidity and without sudden temperature change, acid air, any other harmful air or strong magnetic field.
 Recommend floor life (out of bag) at factory no more than 4 weeks.
- (B) The MEMS MIC with normal pack can be transported by ordinary conveyances. Please protect products against moist, shock, sunburn and pressure during transportation.

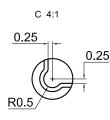
MATERIALS STATEMENT

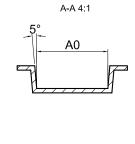
Meet the requirements of MEMSensing standard on hazard substances control (including RoHS2.0+REACH+Halogen-Free, etc.), with "HSF" identification on label.

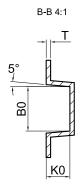


PACKAGING & MARKING DETAIL:

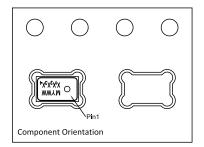








Direction of Feed



| ITEM | W | ш | F | ØD0 | K0 |
|------------------|------------|------------|-----------|-----------------------|--------------------|
| D I M(mm) | 12.00±0.30 | 1.75±0.10 | 5.50±0.10 | 1.50 ^{+0.10} | 1.35±0.10 |
| ITEM | P0 | 10P0 | P1 | A0 | B0 |
| DIM(mm) | 4.00±0.10 | 40.00±0.20 | 8.00±0.10 | 4.06±0.10 | 2.54 <u>+</u> 0.10 |
| ITEM | P2 | Т | | | |
| DIM(mm) | 2.00±0.10 | 0.25±0.05 | | | |

Note:

- 1) Dimensions are in mm;
- 2) Don't put the vacuum suction nozzle alignment the port hole;
- 3) Tape & Reel Per EIA-481 standard;
- 4) Label applied to external package and direct to reel;
- 5) Static voltage <100V;

| Model Number | Reel Diameter | Quantity Per Reel |
|----------------|---------------|-------------------|
| MSM42A3722H9KR | 13 inch | 5700 |



RELIABILITY SPECIFICATIONS

| Test | Description |
|------------------------------|---|
| Thermal Shock | 100 cycles air-to-air thermal shock from -40°C to +125°C with 15 minute soaks. |
| High Temperature Storage | 1,000 hours at +105°C environment |
| Low Temperature Storage | 1,000 hours at -40°C environment |
| Reflow | 5 reflow cycles with peak temperature of +260°C |
| ESD-HBM | 3 discharges of ±2 kV direct contact to I/O pins. |
| ESD- LID-GND | 3 discharges of ±8 kV direct contact to lid while unit is grounded. |
| ESD-MM | 3 discharges of±200V direct contact to I/O pins. |
| Vibration | 4 cycles of 20 to 2,000 Hz sinusoidal sweep with 20 G peak acceleration lasting 12 minutes in X, Y, and Z directions. |
| Mechanical Shock | 3 pulses of 10,000 G in the X, Y and Z direction |
| High Temperature Bias | 1,000 hours at +105°C under bias |
| Low Temperature Bias | 1,000 hours at -40°C under bias |
| Temperature/Humidity Bias | 1,000 hours at +85°C/85% R.H. under bias. |
| Drop Test | To be no interference in operation after dropped to 1.0cm steel plate 18 times from 1.5 meter height |

NOTE: Sensitivity should vary within ± 3 dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at 20 \pm 2 °C, R.H 60% \sim 70%)



| Revision | Subjects (major changes since last revision) | Date |
|----------|--|------------|
| 1.0 | Initial Release | 2019-10-12 |

| 公司销售、技术支持联系方式 | (http://www.memsensing.com) | |
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